

FIG. 1 PRIOR ART

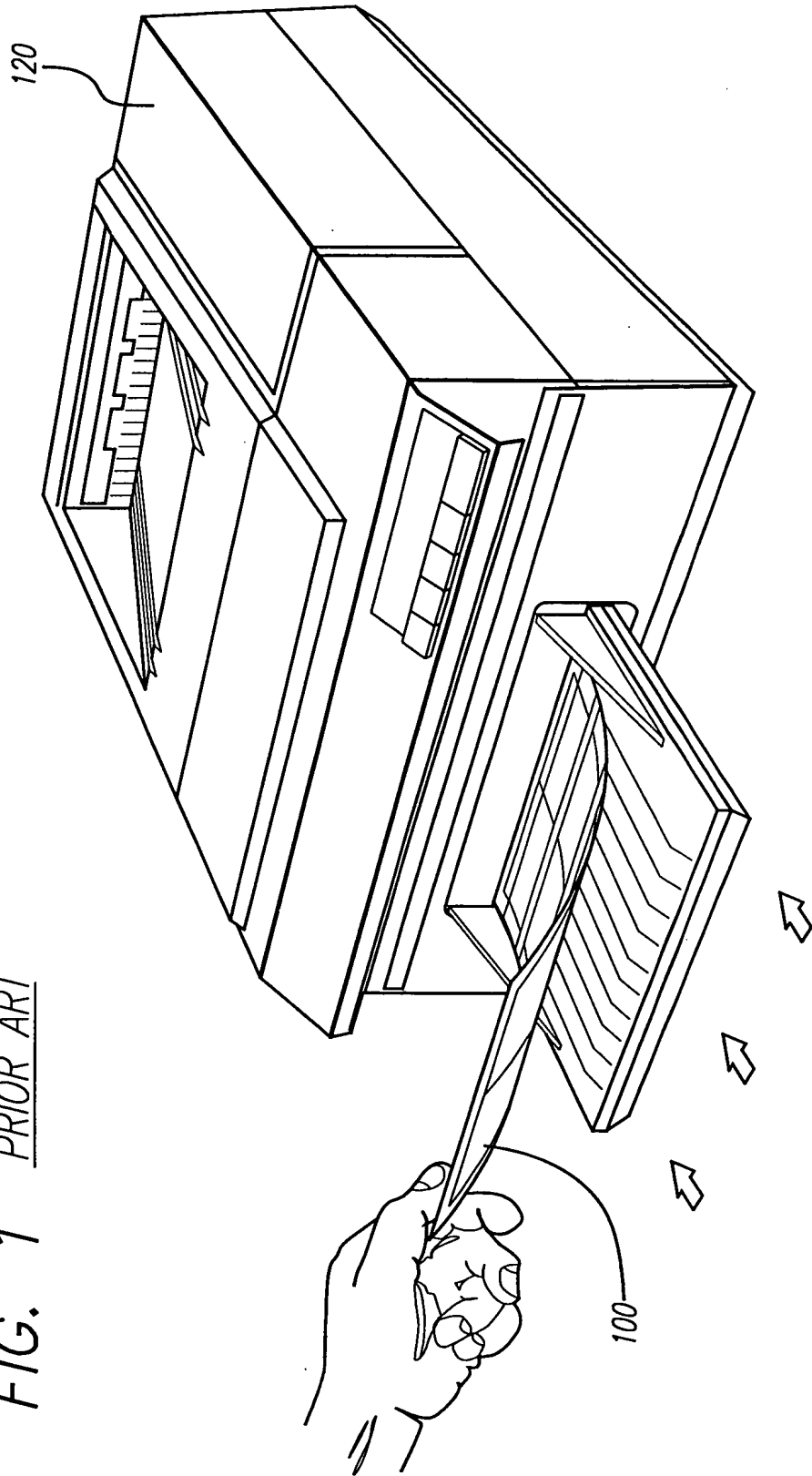


FIG. 2 PRIOR ART

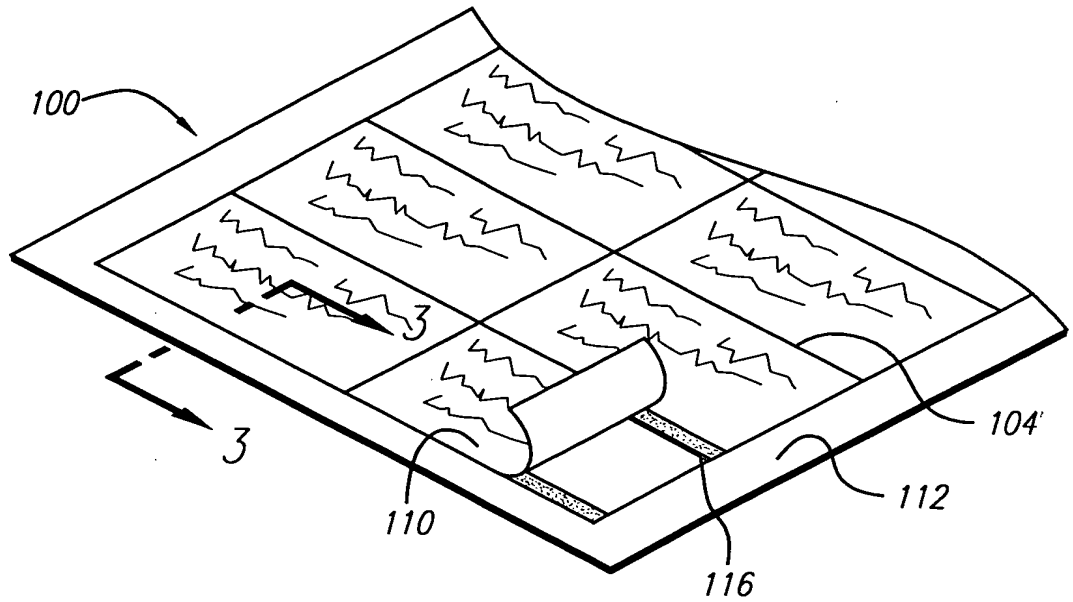
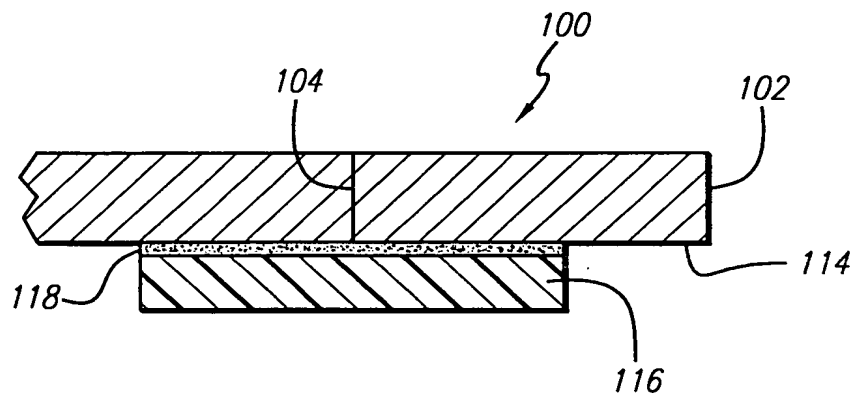
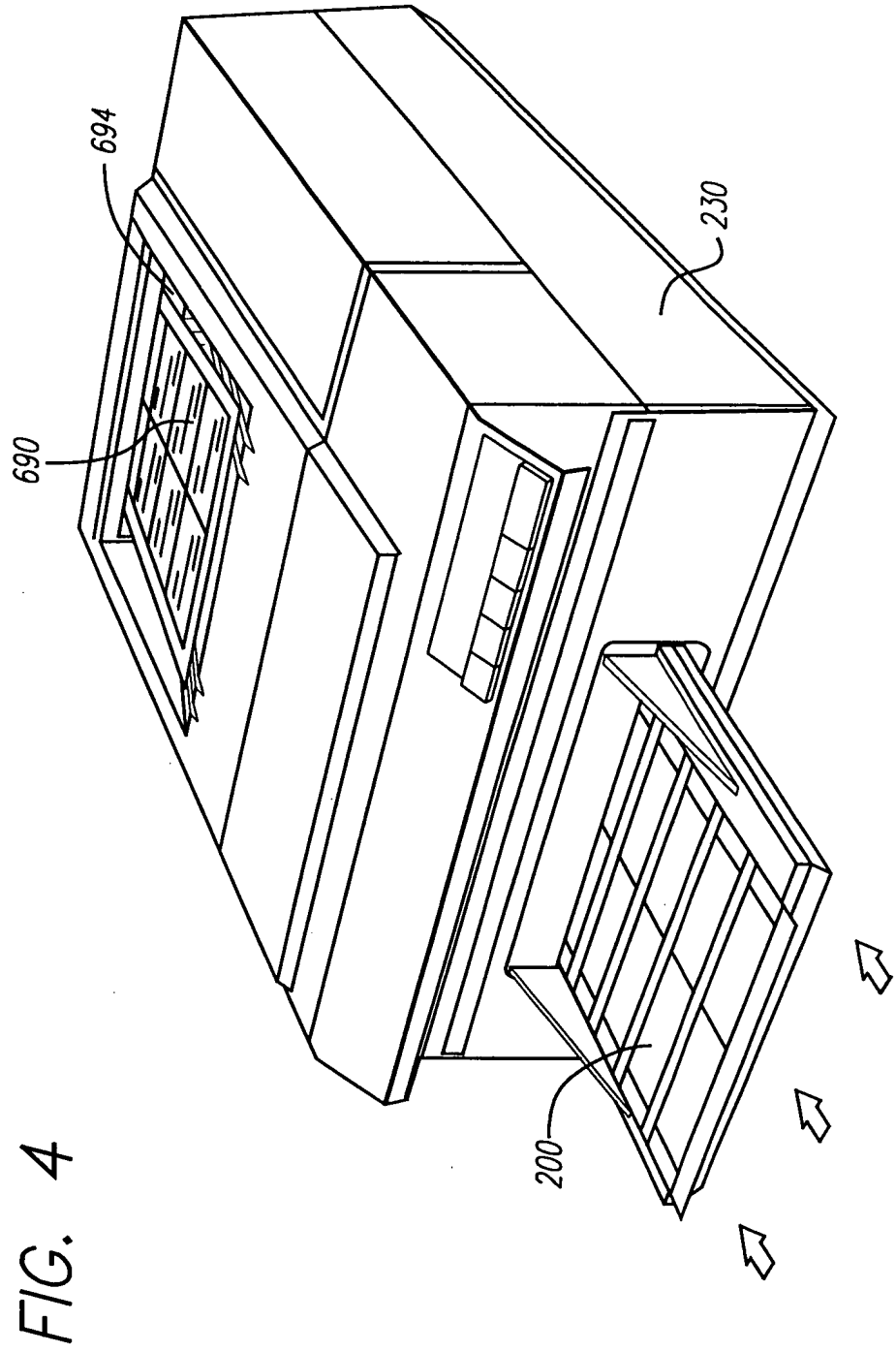
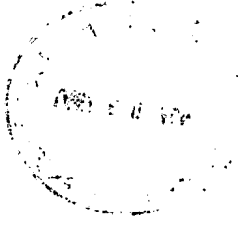


FIG. 3 PRIOR ART





A cross-sectional view of a device assembly 200. The assembly includes a main body 212 with a top surface 240. A layer 224 is disposed on the top surface 240. A component 234 is attached to the side of the main body 212. A layer 216 is disposed on the bottom surface of the main body 212. A component 300 is attached to the bottom surface of the main body 212. A layer 208 is disposed on the bottom surface of the component 300. A layer 204 is disposed on the bottom surface of the main body 212.

FIG. 13

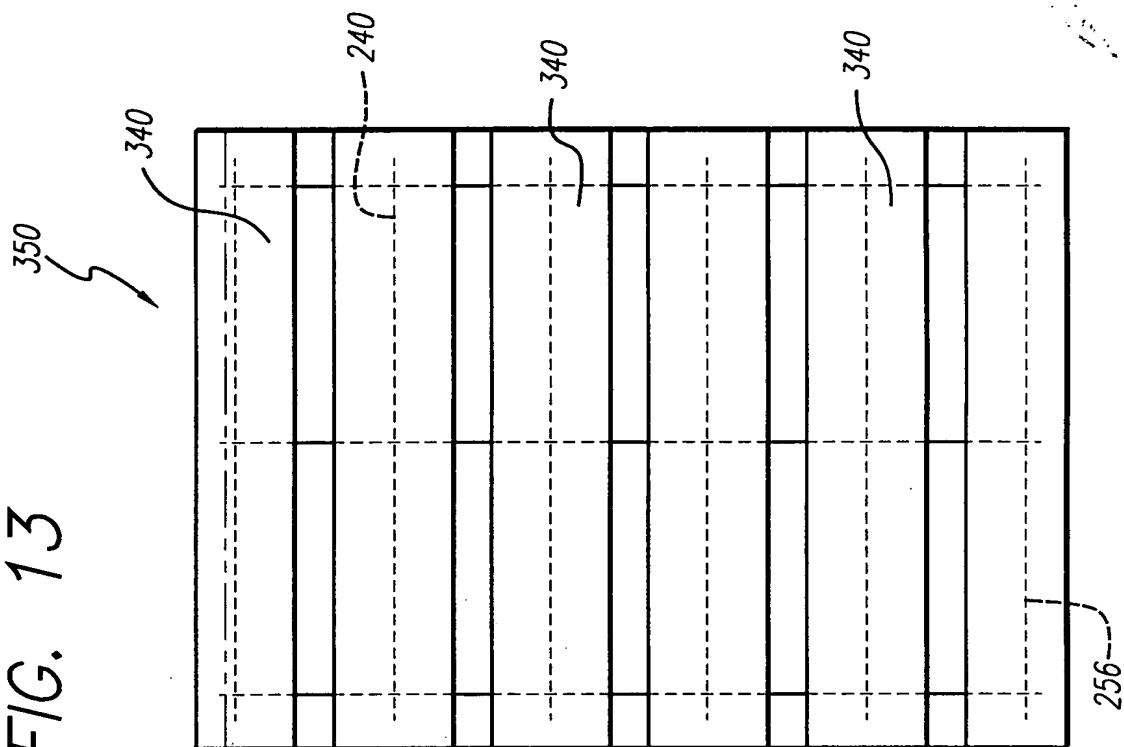


FIG. 7

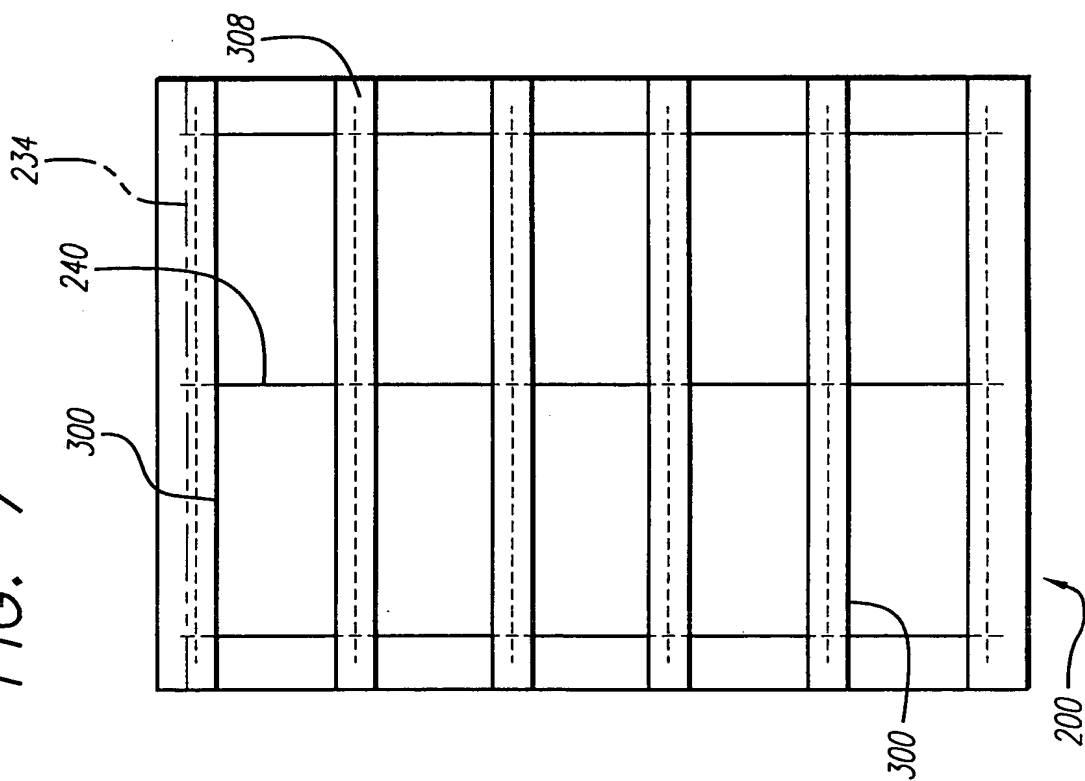


FIG. 8

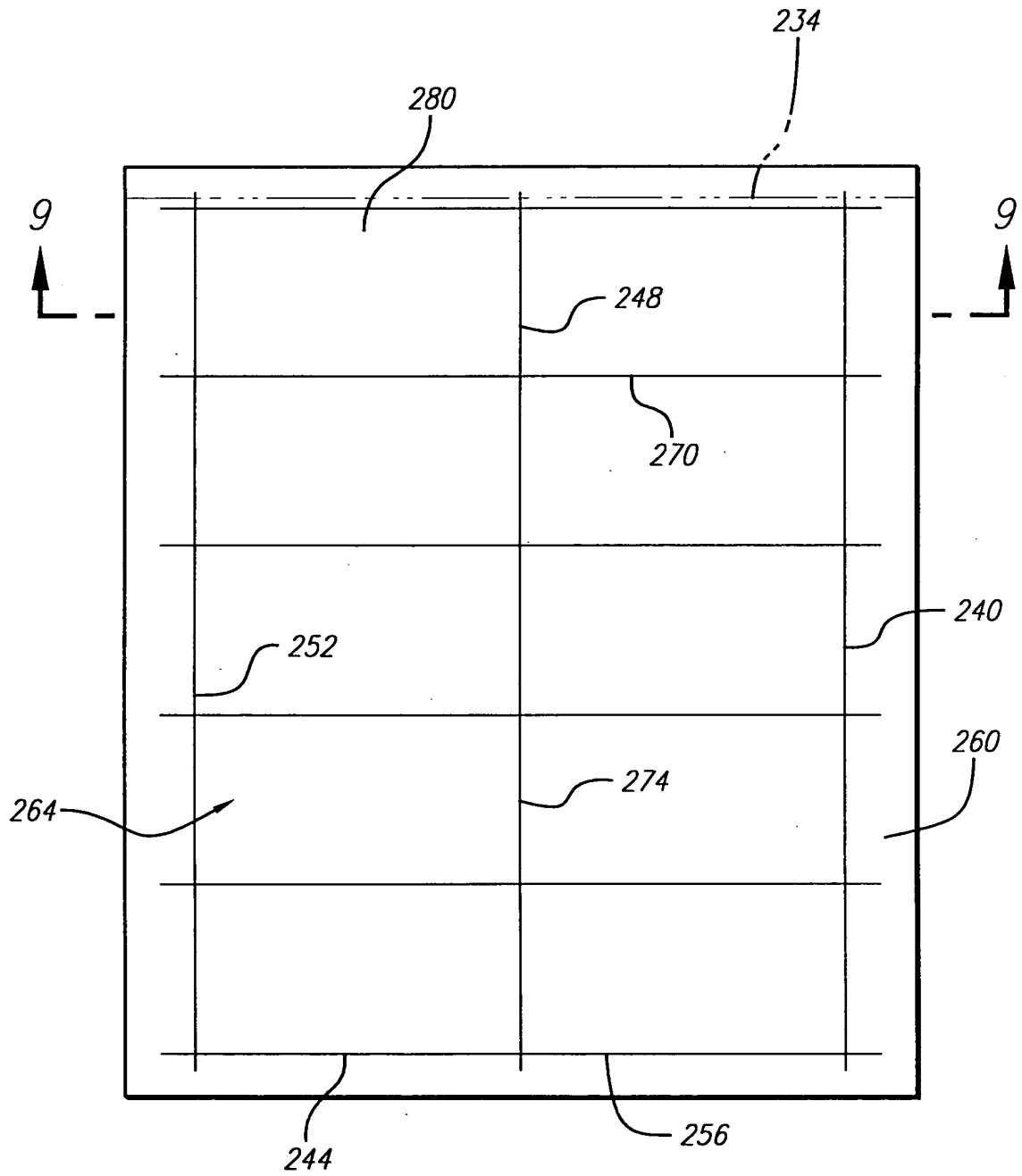
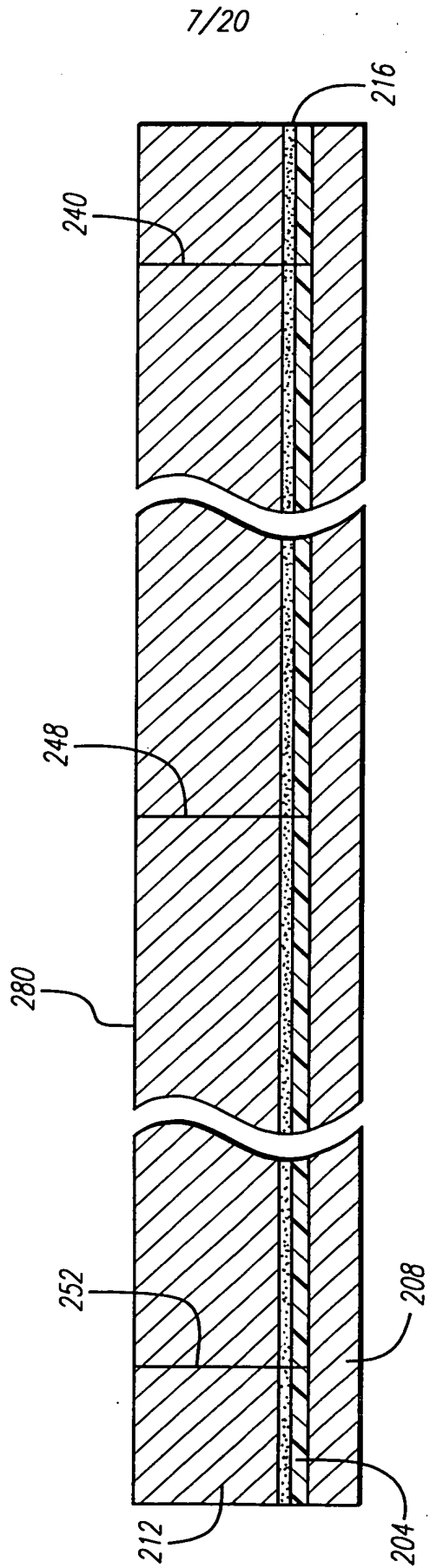


FIG. 9



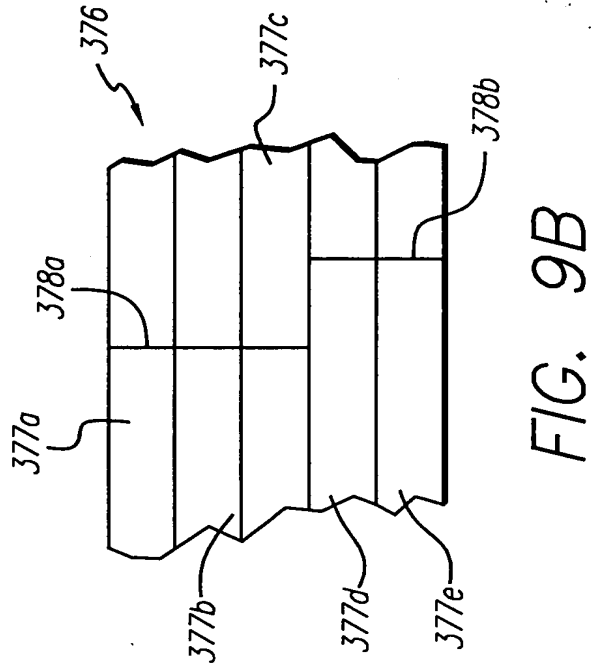
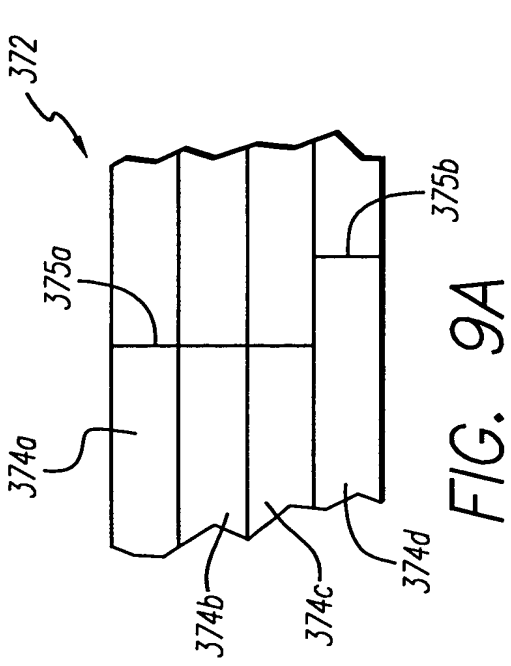
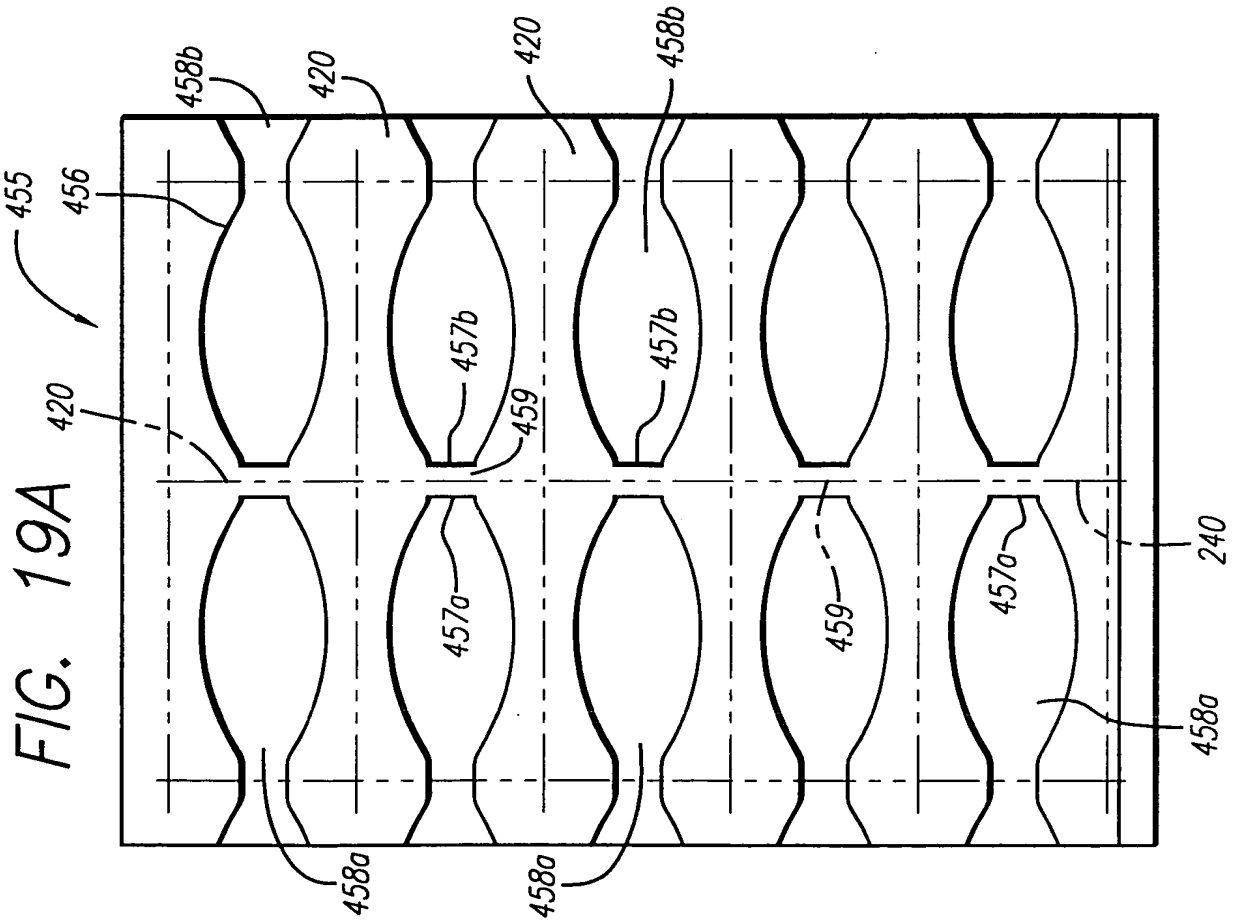




FIG. 10

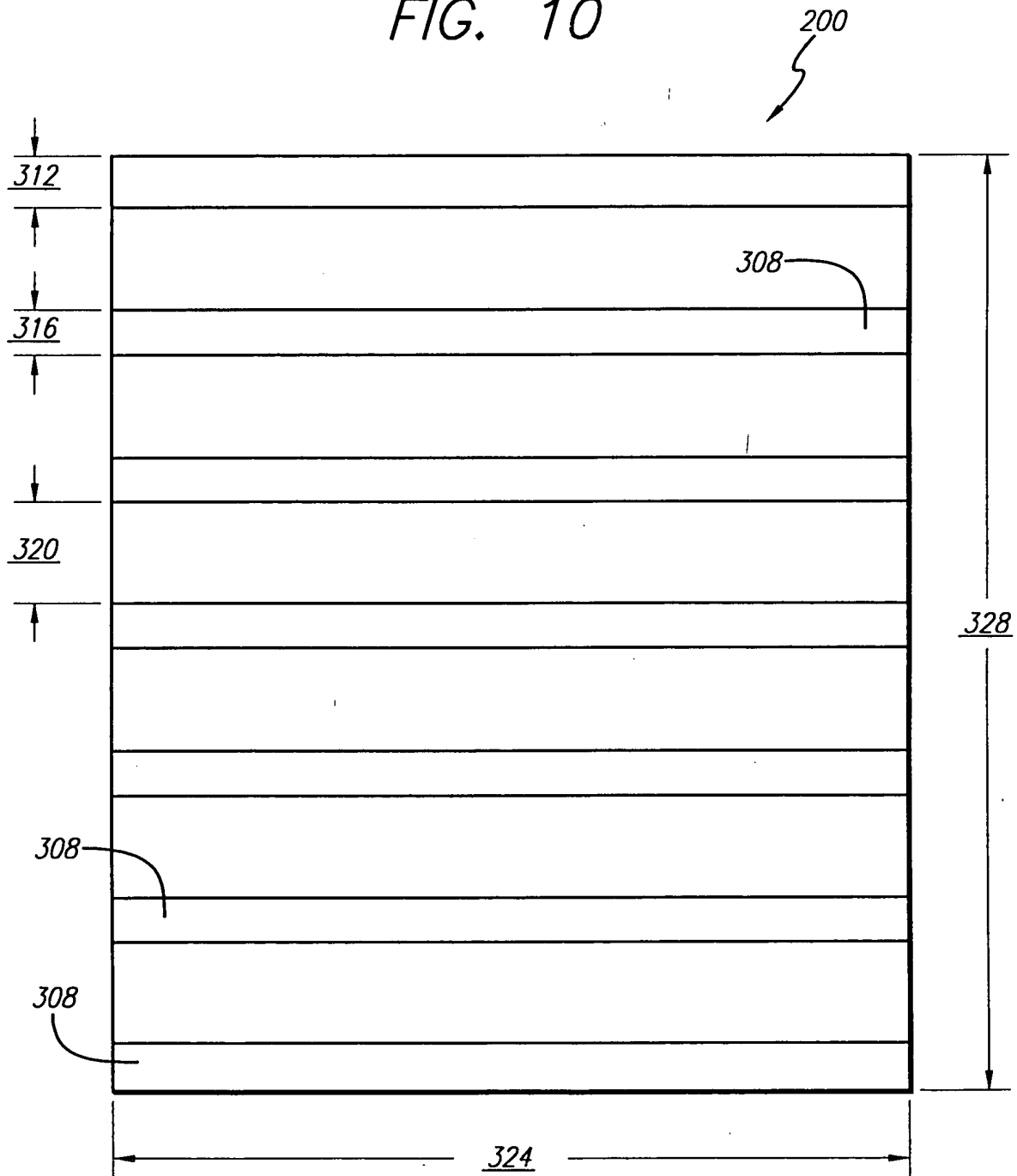
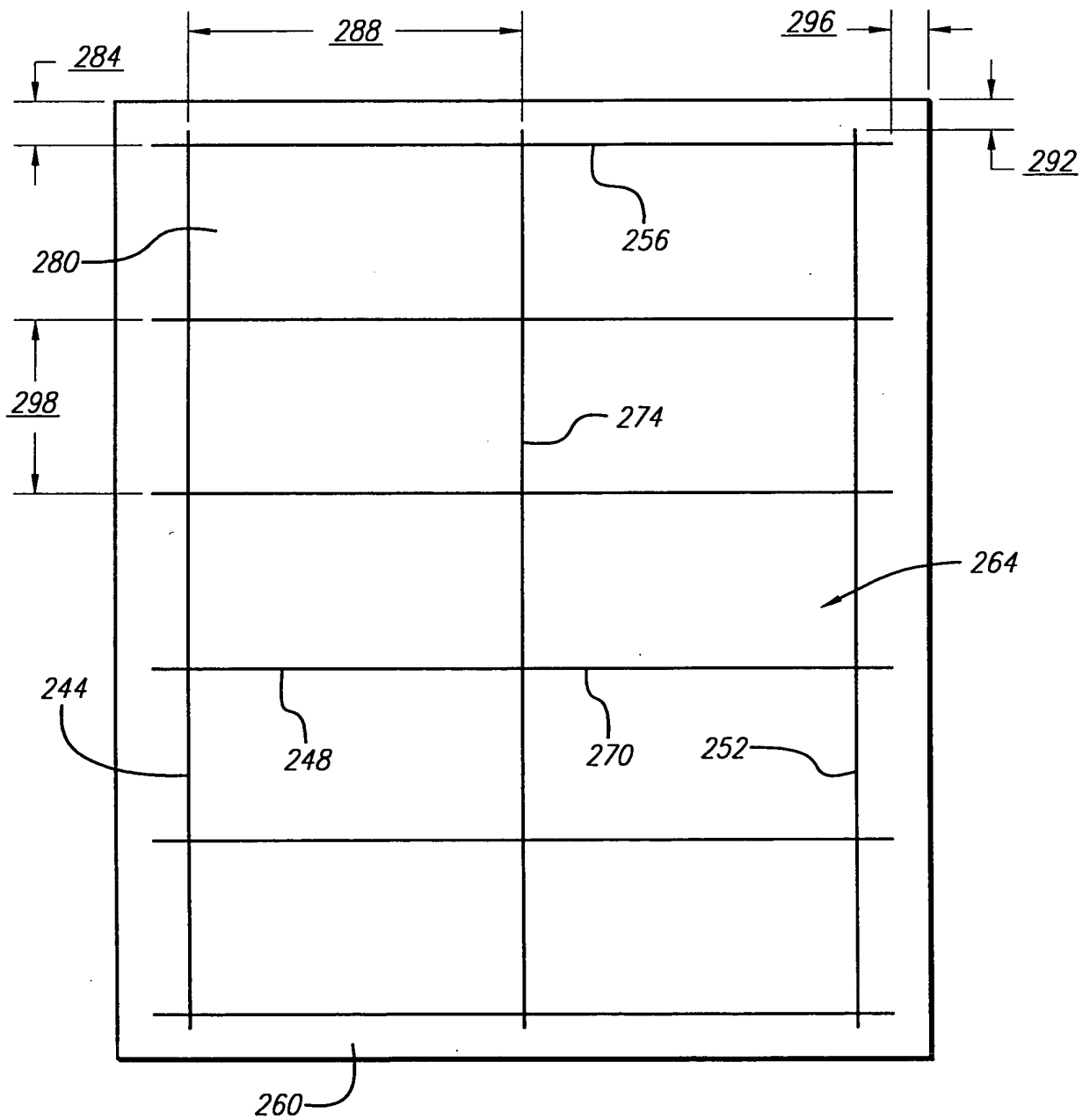


FIG. 11



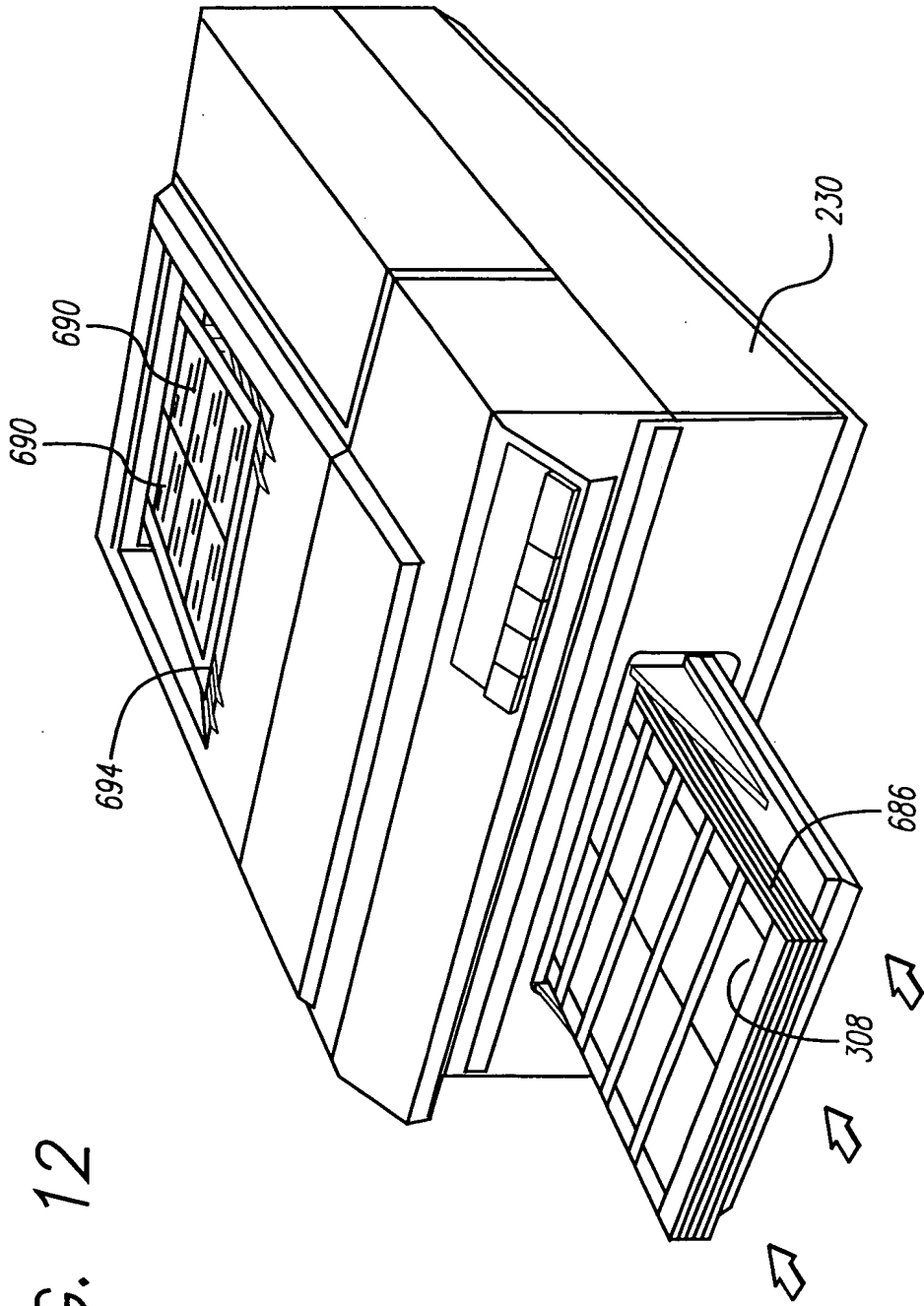


FIG. 12

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FIG. 14

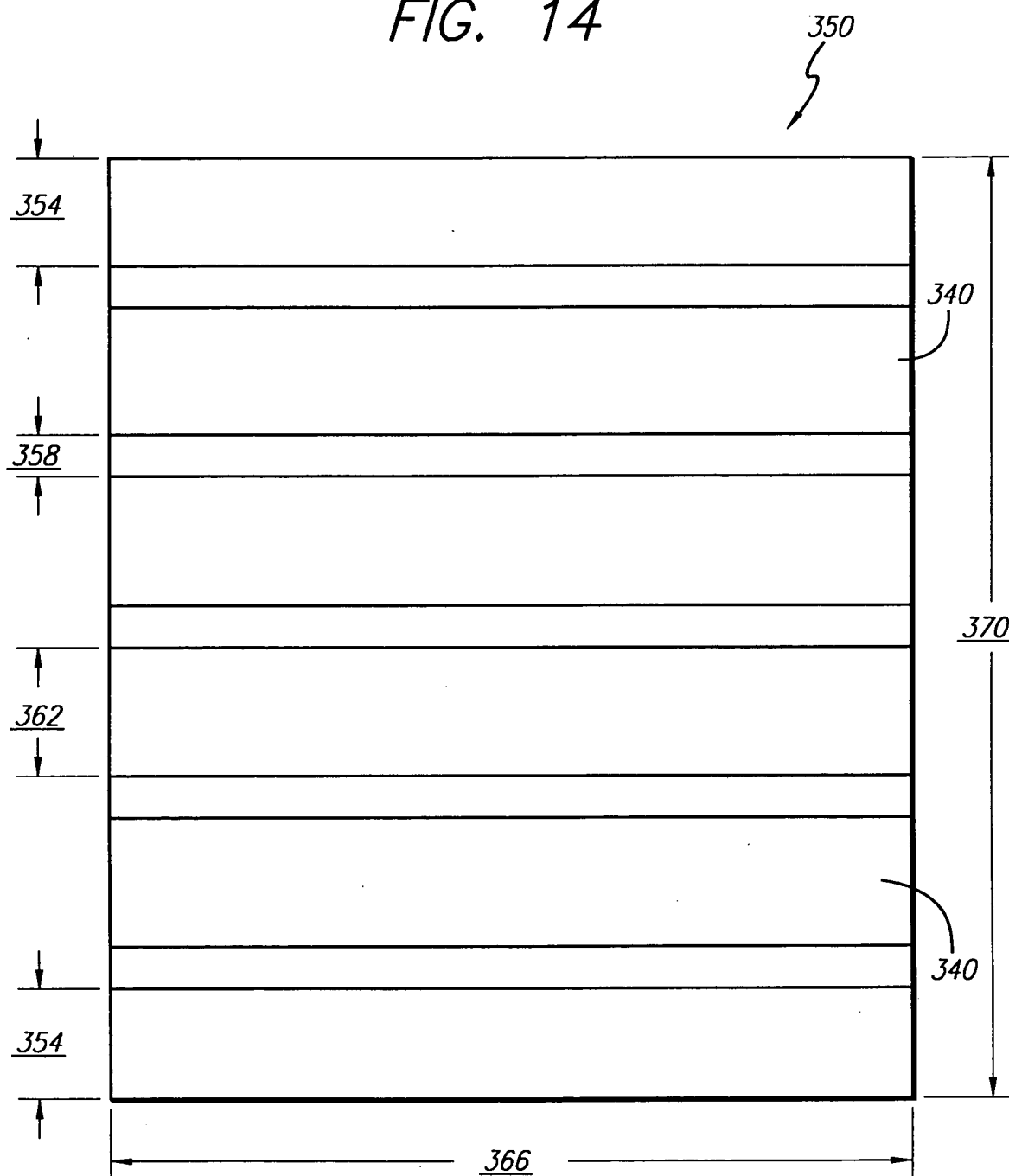


FIG. 19

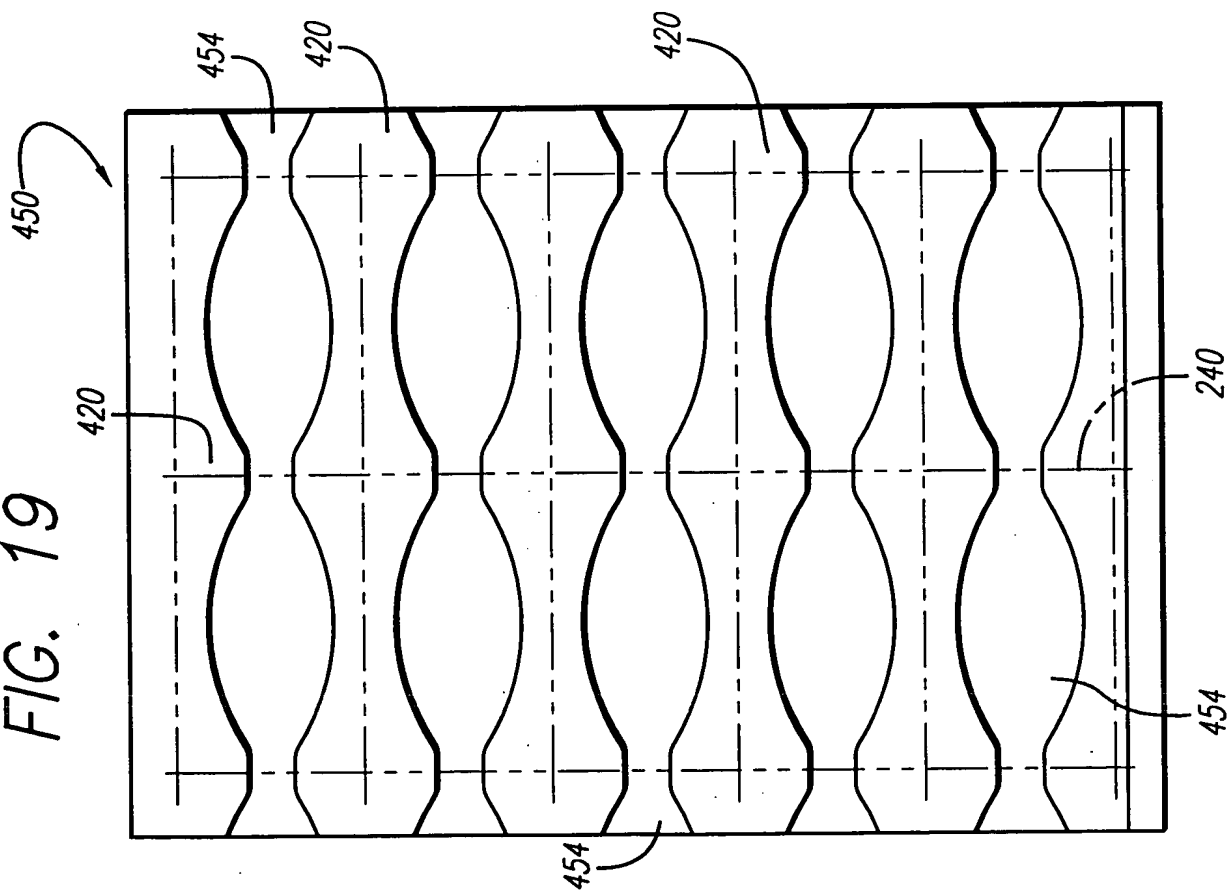
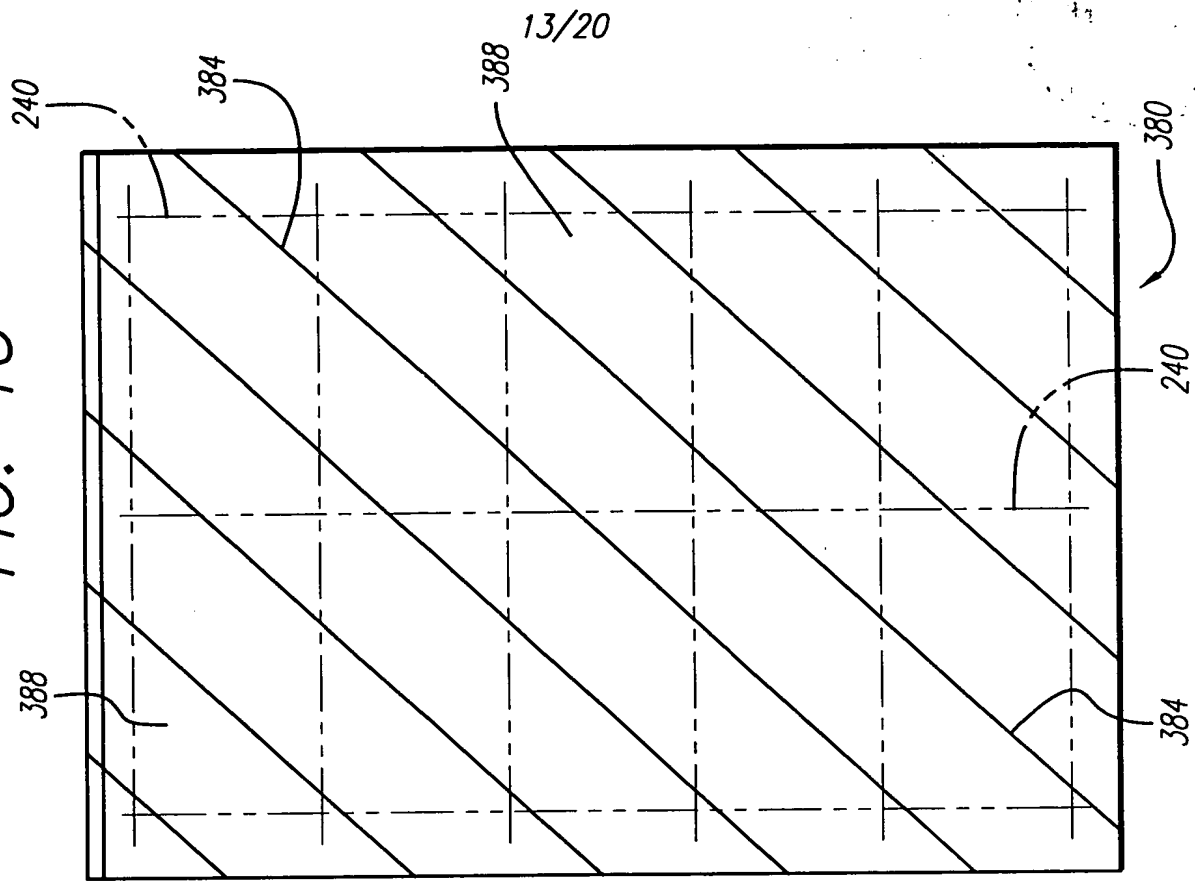


FIG. 15



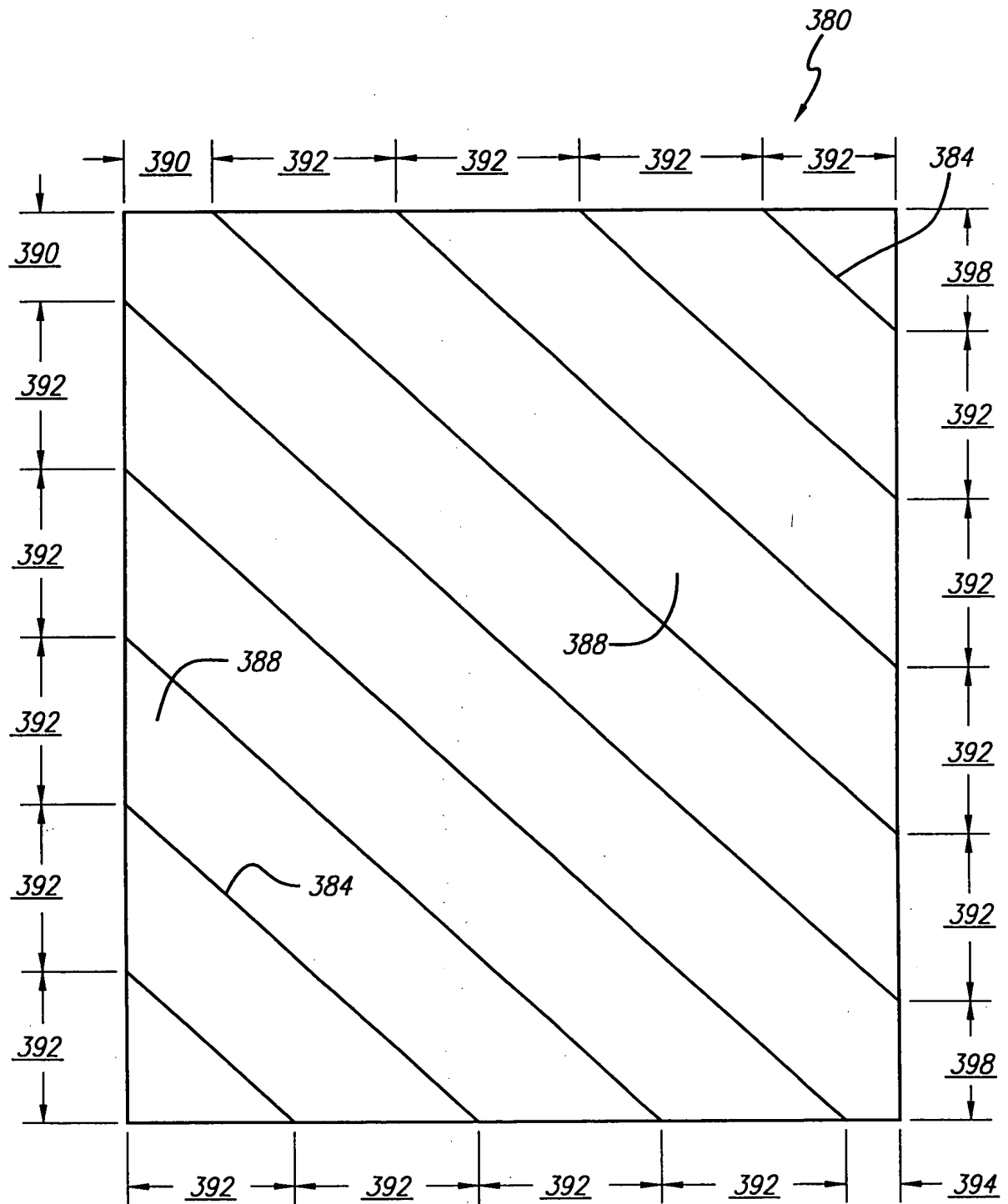


FIG. 16

FIG. 17

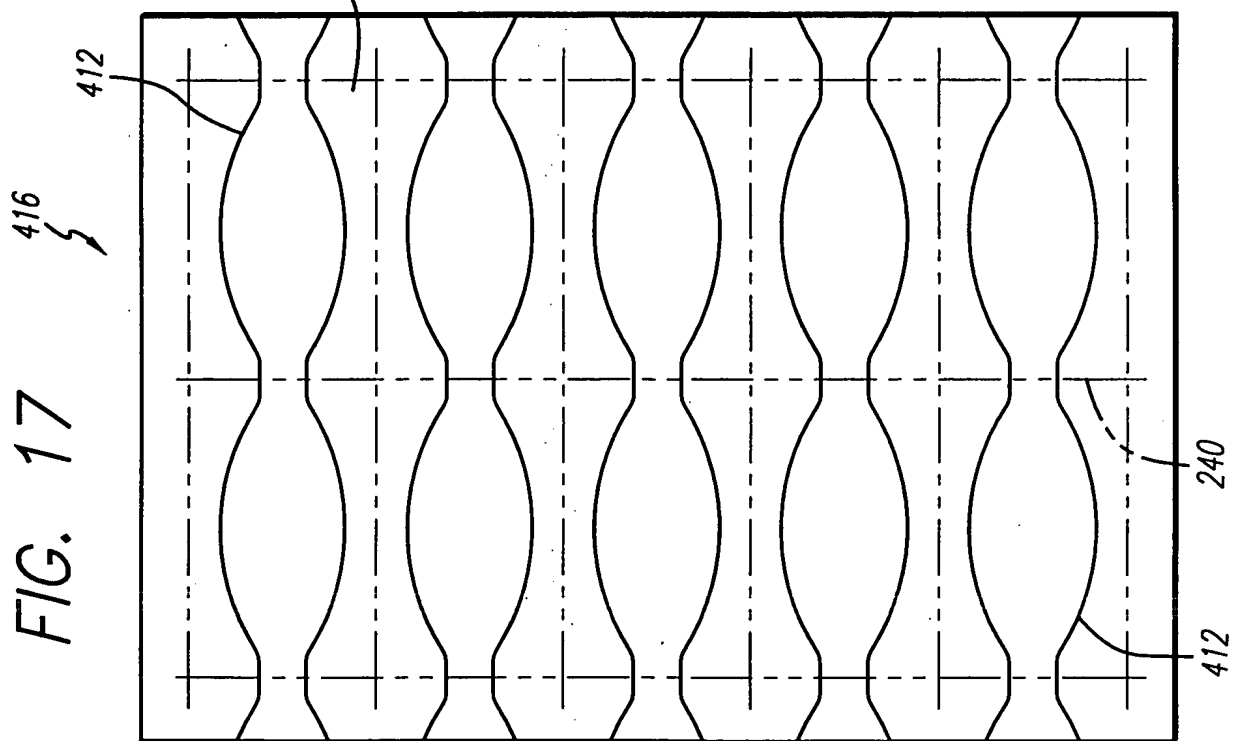


FIG. 23

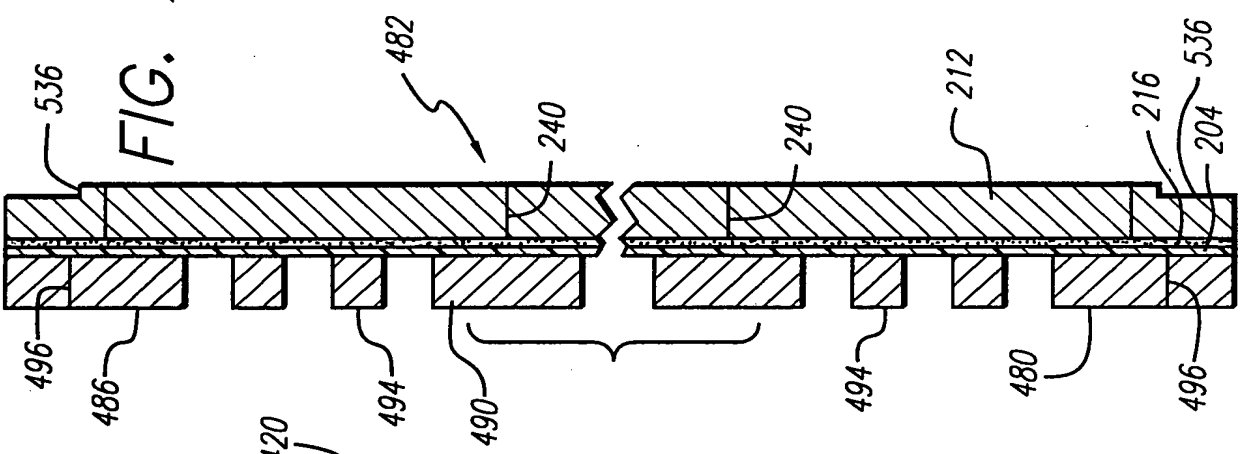


FIG. 24

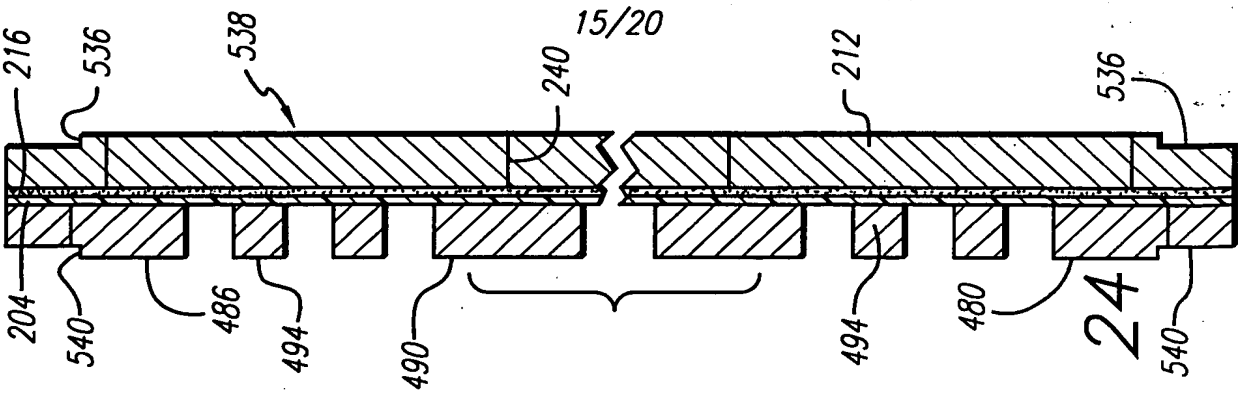
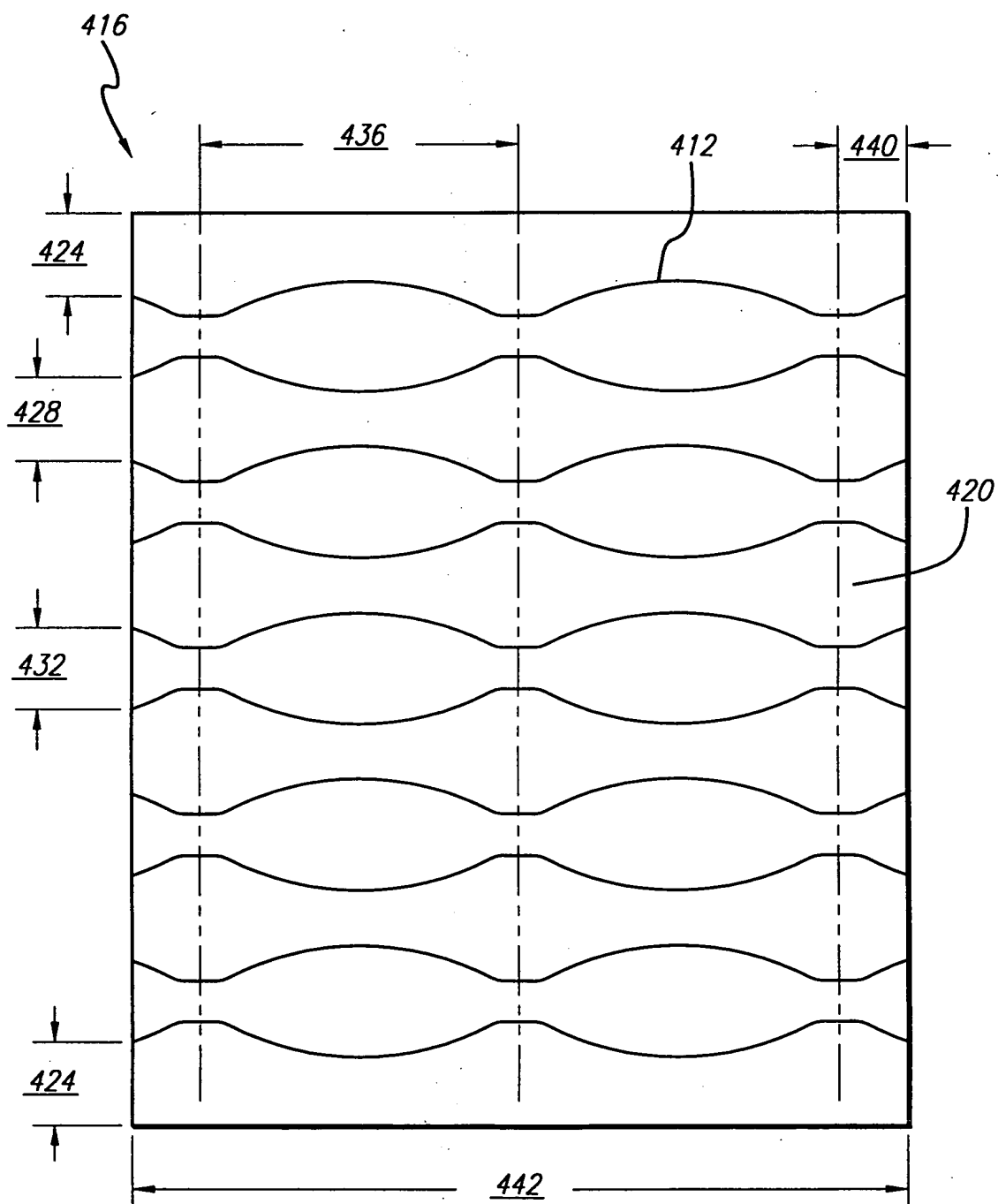
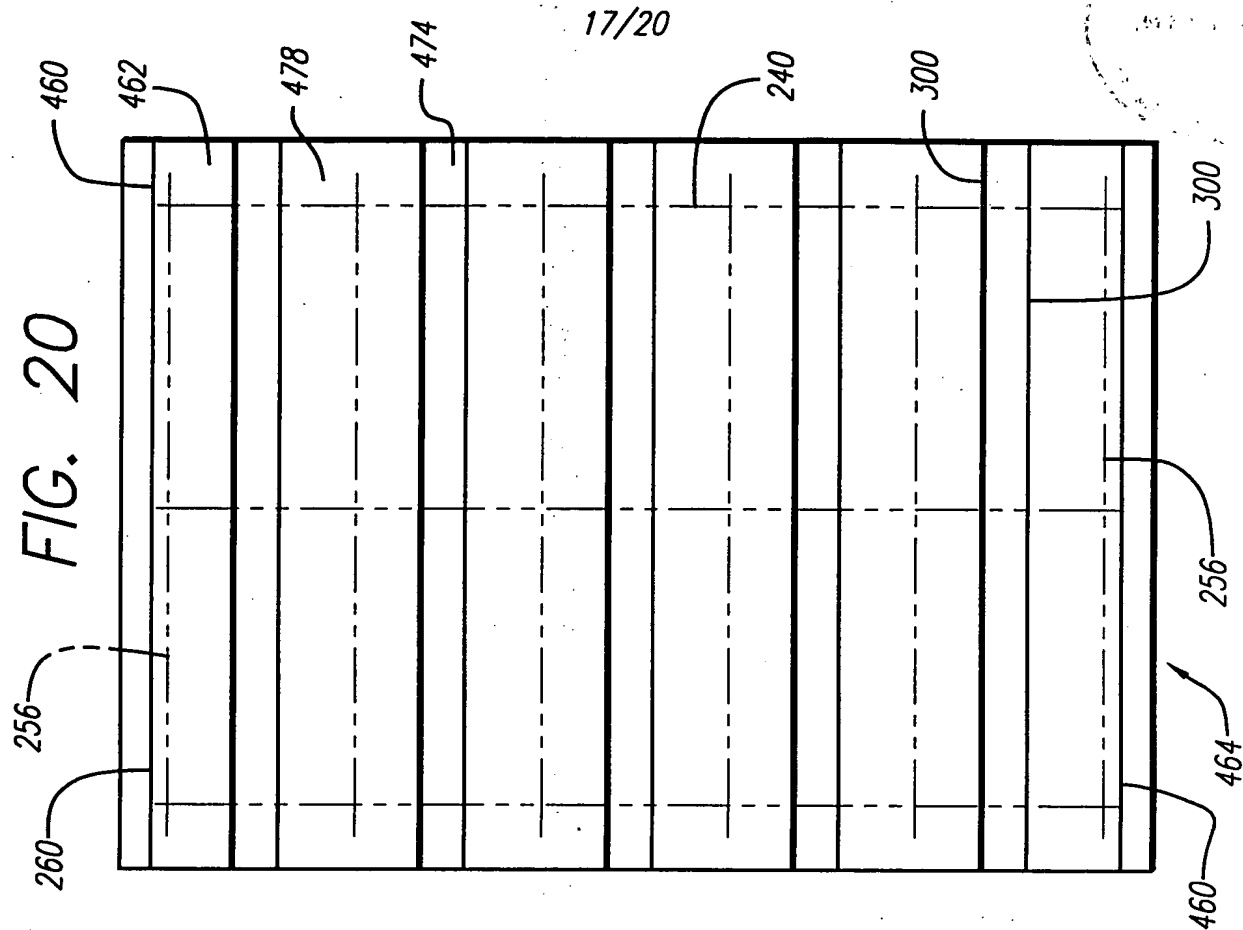
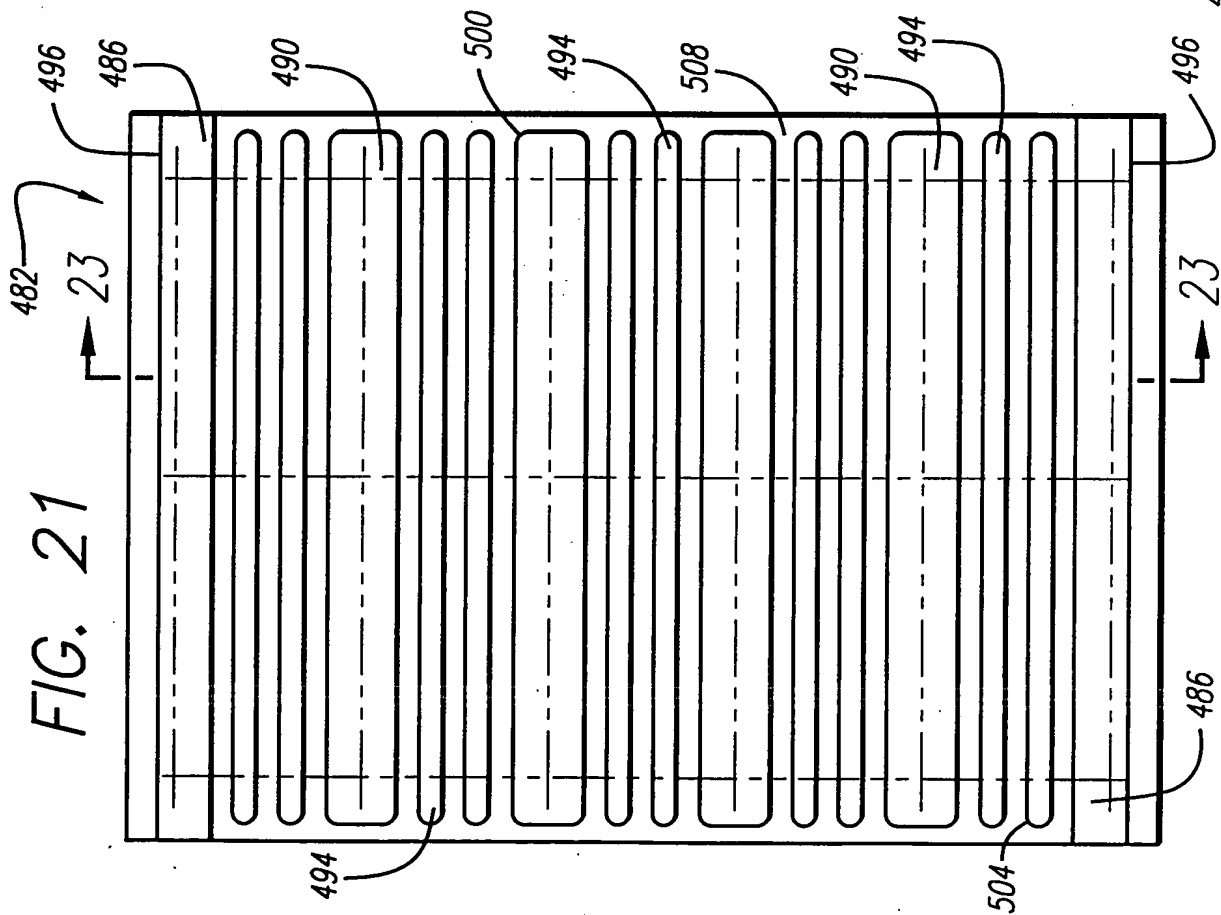


FIG. 18







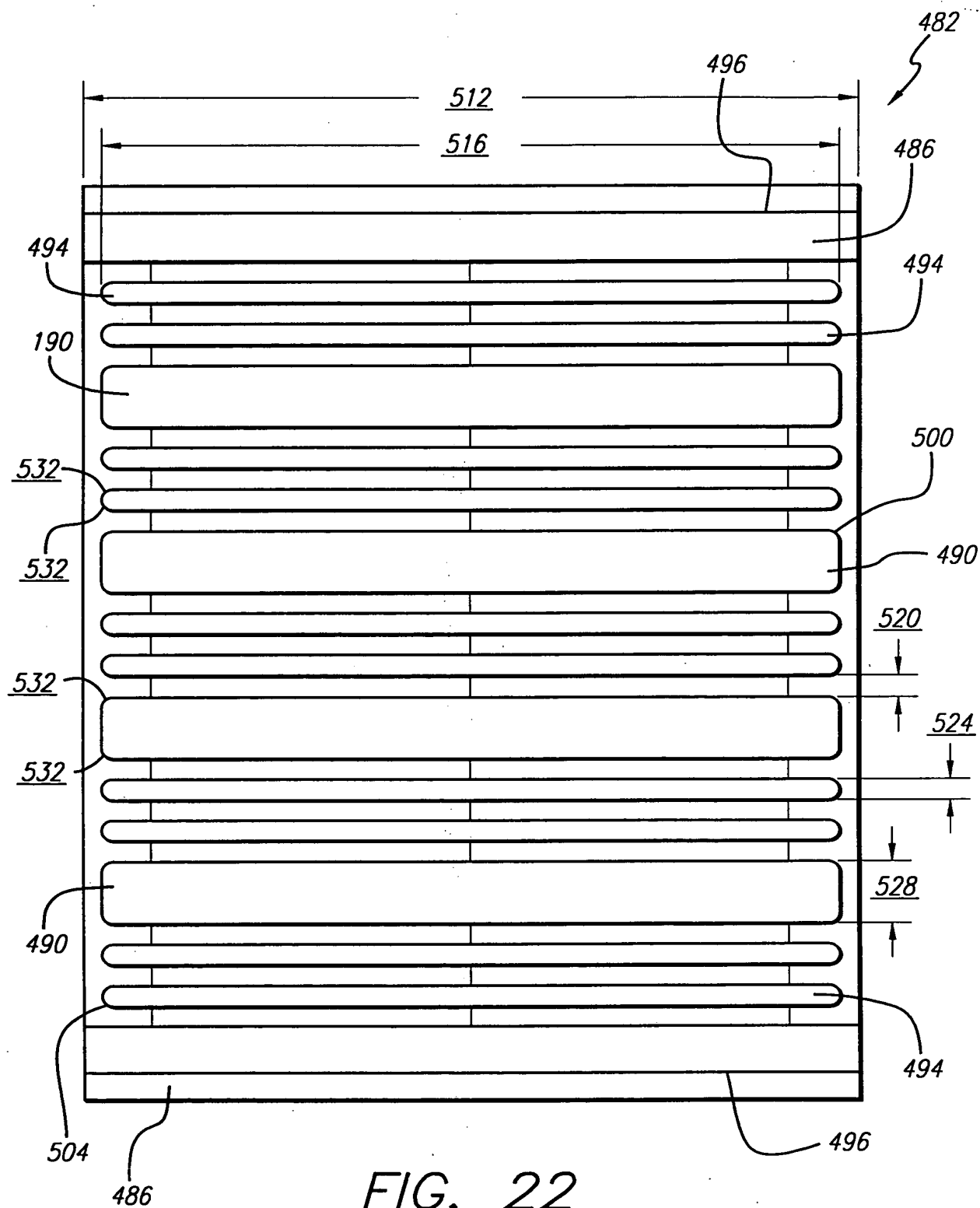


FIG. 22

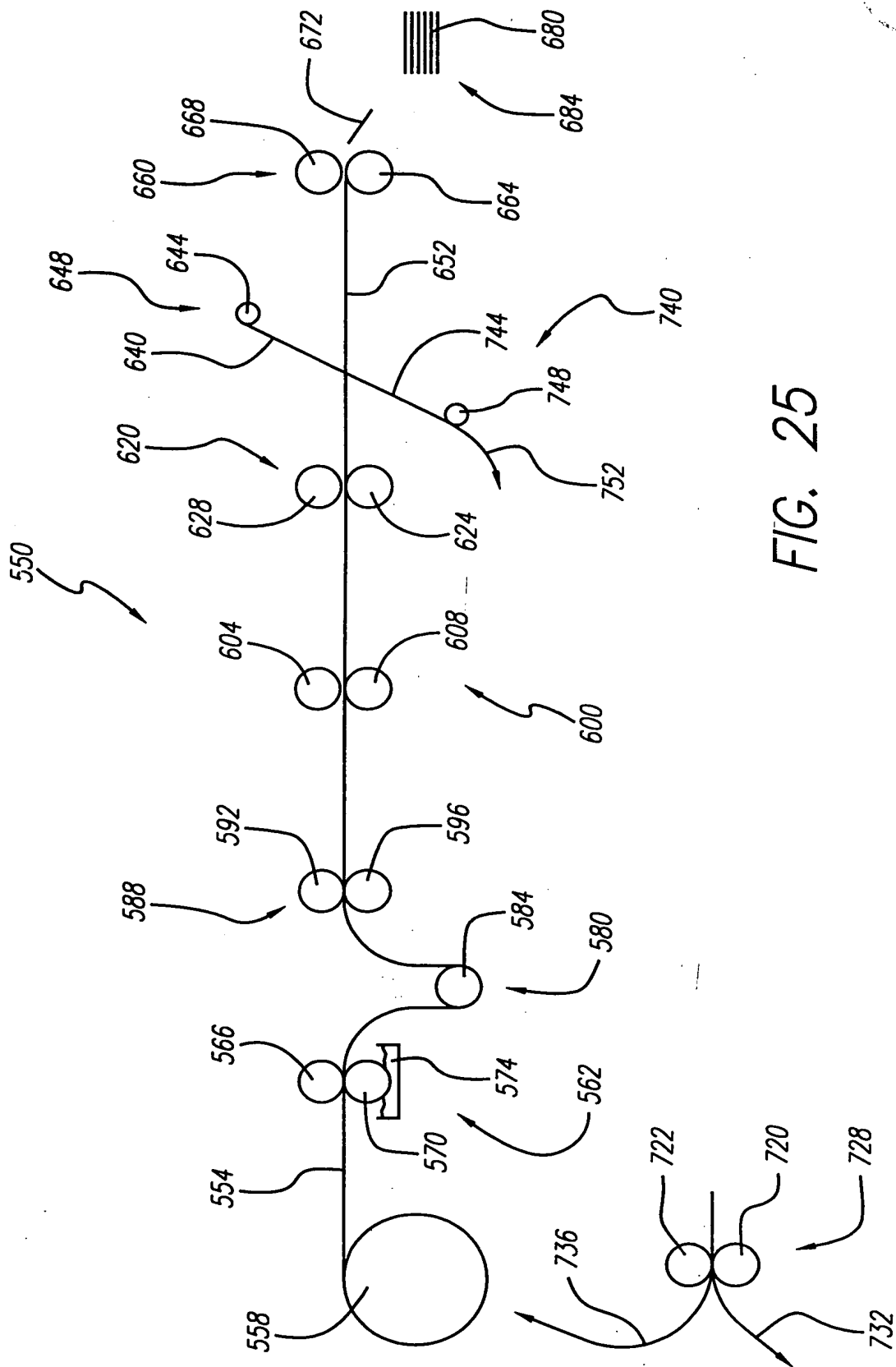


FIG. 25

FIG. 26

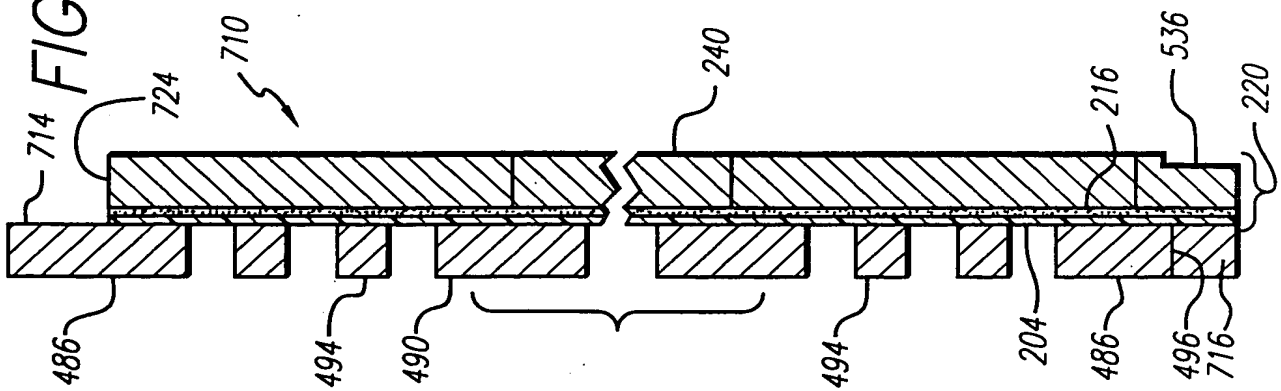


FIG. 27

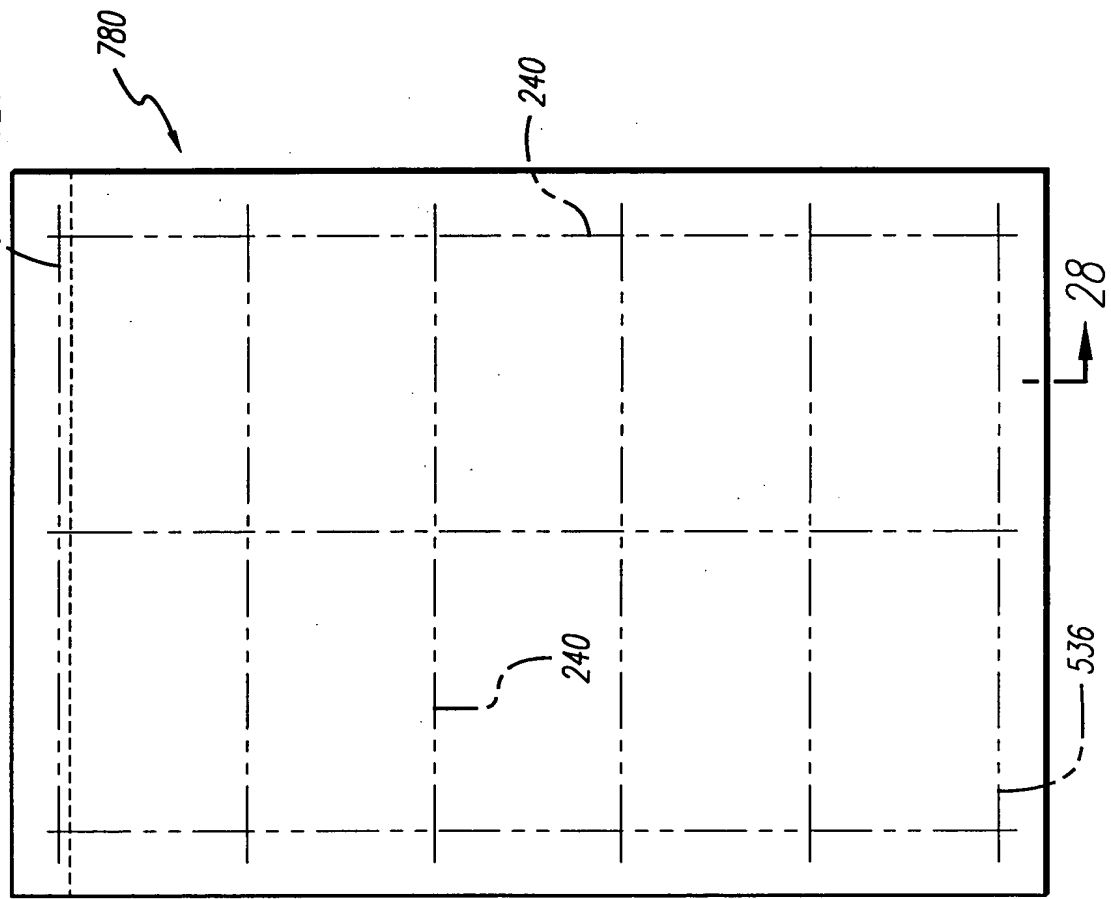


FIG. 28

